

ABSTRACT OF THE DISCLOSURE

The present invention to provide a method of mounting a semiconductor laser component capable of preventing deterioration of laser characteristics and destruction of the semiconductor laser component due to residual stresses as well as preventing decrease of a lifetime due to increase in temperature of the semiconductor laser component.

The method of mounting a semiconductor laser device which comprises a step of pressure bonding a semiconductor laser component on a submount by a collet while a bonding member is heated to be fused or melt on a submount by heating a table on which the submount is placed, for example, characterized in that the table and the collet are heated to a temperature higher than a fusing point of said bonding member so as not to occur the heat transfer substantially to a collet, and then heating of the table and the collet is terminated with maintaining the pressure bonding state.